IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Patent Application of: Kuei-Wu Huang, et al.

Serial No.: 10/687,713 Group Art Unit: 1765

Filed: October 17, 2003 Examiner: L. Vinh

For: SURFACE TREATED LOW-K DIELECTRIC AS DIFFUSION BARRIER FOR COPPER METALLIZATION

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT AND RESPONSE

Sir:

In response to the Office Action of June 28, 2006, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.